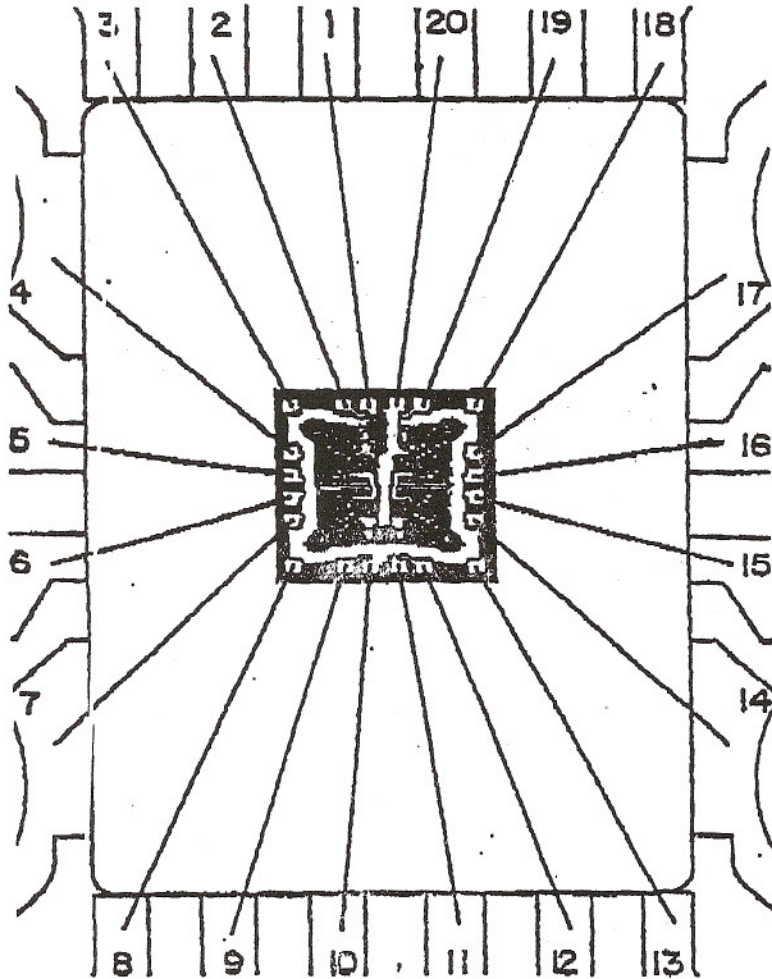




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below.



PAD NO	FUNCTIONS
1	MR
2	Q0
3	D0
4	D1
5	Q1
6	Q2
7	D2
8	D3
9	Q3
10	GND

PAD NO	FUNCTIONS
11	CP
12	Q4
13	D4
14	D5
15	Q5
16	Q6
17	D6
18	D7
19	Q7
20	VCC

Topside Metal: Aluminum
Backside Metal: Silicon
Backside Potential:
Mask Ref: Issue 1
Bond Pads (Mils): .004 Min.

APPROVED BY:
MFG: Motorola Semi

DIE SIZE: .060" X .061"
THICKNESS: .015"

DATE: 3/10/00
P/N: 54LS273